

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-11 (Canceled)

Claim 12 (New) Method of manufacturing a multi-layer pc board for the assembly of electronic devices, the pc board comprising at least one layer whose thermal expansion properties correspond approximately to the thermal expansion properties of the electronic devices and, at the same time, determine essentially the thermal expansion properties of the multi-layer pc board, the method comprising:

joining a thin glass foil to at least one other layer of the multi-layer pc board via a resin formulation and pressing so as to form a laminate, wherein the thin glass foil is configured as a borosilicate glass layer and has a thickness of 30 micrometers to 1100 micrometers.

Claim 13 (New) Method according to Claim 12, wherein a thickness of said thin glass foil is selected in the range from 50 micrometers to 500 micrometers.

Claim 14 (New) Method according to Claim 13, wherein the at least one other layer is made of thermoplastic, thermosetting materials, metals, electrically conducting synthetic resins, or electrically non-conducting synthetic resins.

Claim 15 (New) Method according to Claim 14, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 16 (New) Method according to Claim 14, wherein said thin glass foil is disposed inside or as an outside layer of said multi-layer pc board.

Claim 17 (New) Method according to Claim 16, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 18 (New) Method according to Claim 16, wherein said thin glass foil is used as reinforcing material for laminates and prepgs and/or as an outside layer in combination with thermoplastic or thermosetting polymers.

Claim 19 (New) Method according to Claim 18, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 20 (New) Method according to Claim 14, wherein said thin glass foil is used as reinforcing material for laminates and preprints and/or as an outside layer in combination with thermoplastic or thermosetting polymers.

Claim 21 (New) Method according to Claim 13, wherein said thin glass foil is disposed inside or as an outside layer of said multi-layer pc board.

Claim 22 (New) Method according to Claim 21, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 23 (New) Method according to Claim 21, wherein said thin glass foil is used as reinforcing material for laminates and preprints and/or as an outside layer in combination with thermoplastic or thermosetting polymers.

Claim 24 (New) Method according to Claim 23, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 25 (New) Method according to Claim 21, wherein said thin glass foil is used as reinforcing material for laminates and preprints and/or as an outside layer in combination with thermoplastic or thermosetting polymers.

Claim 26 (New) Method according to Claim 13, wherein said thin glass foil is used as reinforcing material for laminates and preprints and/or as an outside layer in combination with thermoplastic or thermosetting polymers.

Claim 27 (New) Method according to Claim 26, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 28 (New) Method according to Claim 13, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 29 (New) Method according to Claim 12, wherein the at least one other layer is made of thermoplastic, thermosetting materials, metals, electrically conducting synthetic resins, or electrically non-conducting synthetic resins..

Claim 30 (New) Method according to Claim 29, wherein said thin glass foil is disposed inside or as an outside layer of said multi-layer pc board.

Claim 31 (New) Method according to Claim 30, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 32 (New) Method according to Claim 30, wherein said thin glass foil is used as reinforcing material for laminates and prepgs and/or as an outside layer in combination with thermoplastic or thermosetting polymers.

Claim 33 (New) Method according to Claim 32, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 34 (New) Method according to Claim 29, wherein said thin glass foil is used as reinforcing material for laminates and prepgs and/or as an outside layer in combination with thermoplastic or thermosetting polymers.

Claim 35 (New) Method according to Claim 34, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 36 (New) Method according to Claim 29, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 37 (New) Method according to Claim 12, wherein said thin glass foil is disposed inside or as an outside layer of said multi-layer pc board.

Claim 38 (New) Method according to Claim 37, wherein said thin glass foil is used as reinforcing material for laminates and prepgs and/or as an outside layer in combination with thermoplastic or thermosetting polymers.

Claim 39 (New) Method according to Claim 38, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 40 (New) Method according to Claim 37, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 41 (New) Method according to Claim 12, wherein said thin glass foil is used as reinforcing material for laminates and prepgs and/or as an outside layer in combination with thermoplastic or thermosetting polymers.

Claim 42 (New) Method according to Claim 41, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.

Claim 43 (New) Method according to Claim 12, wherein said thin glass foil is perforated, rendered porous, structured for optical applications, imprinted, physically coated, chemically coated, processed in a roll-to-roll process and/or thermally moulded.